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# 熱流商用軟體介紹與應用

## Introduction to CFD Commercial Software on Electronics

(I)

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2001/12/28

# Course Outline (2001/12/28)

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- The Requirement of CFD Software on Electronics
- The Elements of CFD Software
- The Applications
- Introduction to FLOTHERM®

# Course Outline (2002/1/4)

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- The Virtual vs. the Reality
- The Challenges of Commercial CFD Software
- Q&A

# Course Outline (2001/12/28)

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- **The Requirement of CFD Software on Electronics**
- The Elements of CFD Software
- The Applications
- Introduction to FLOTHERM®

# The Requirement of CFD Software on Electronics

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- **Platform**

  - Supper Computer

  - Unix Workstation

  - PC (Windows, Linux)

  - Parallel solver (PC cluster)

- **Users Interface (GUI)**

  - Pre-processing

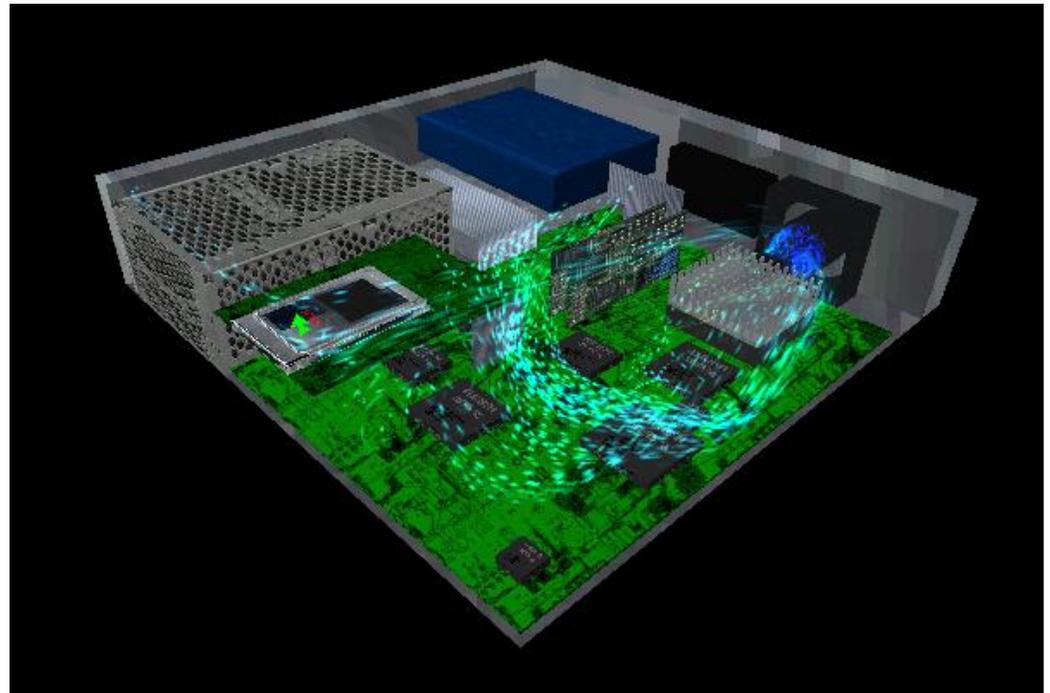
    - No text editing

    - Customization

  - Post-processing

    - Visualization

    - Virtual Reality



# The Requirement of CFD Software on Electronics

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- **Solver**

Faster

More accuracy

More capabilities

Specialization

- **Others**

Reporting

The interface to CAD and CAE software

The Relative Database

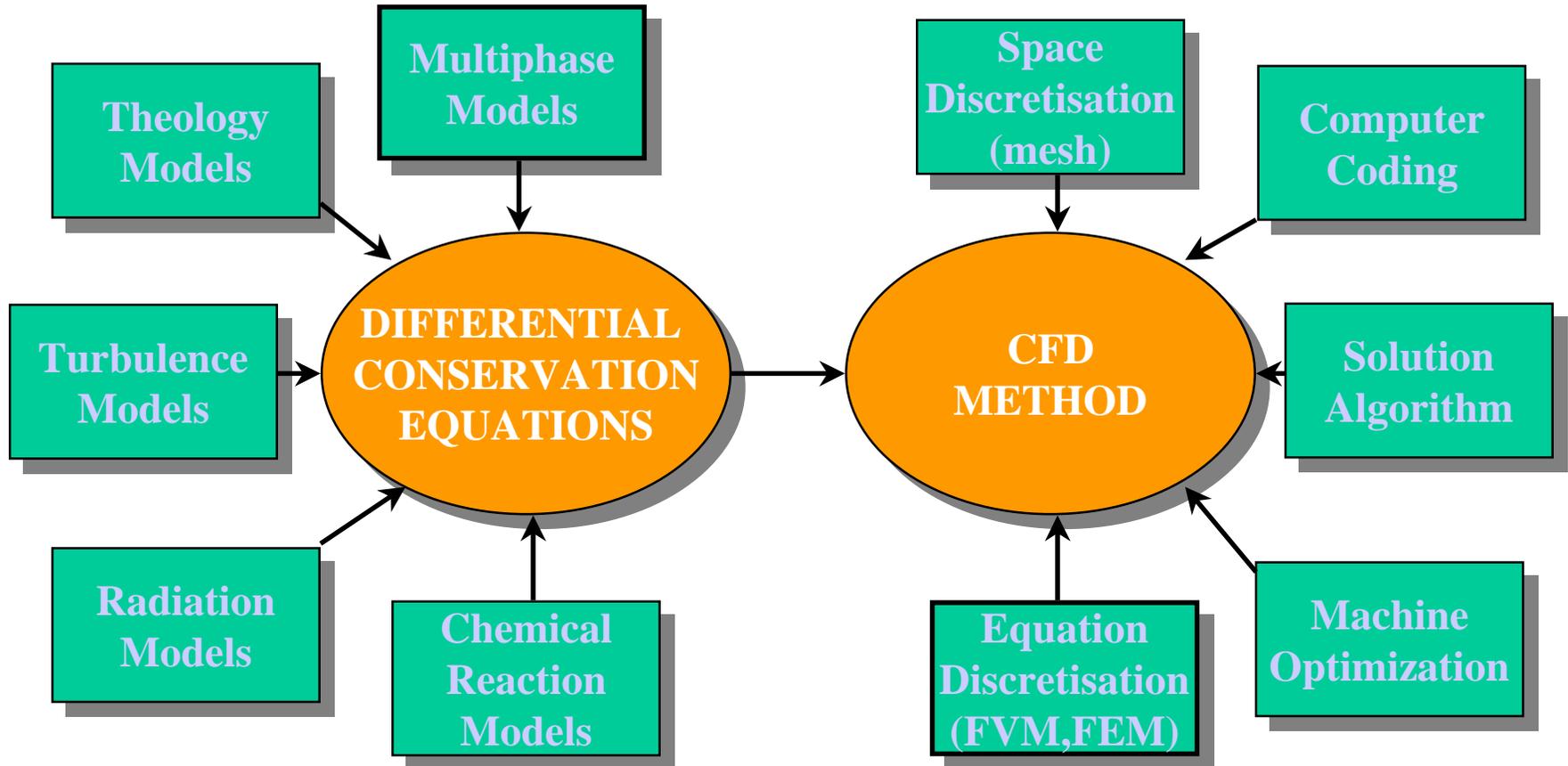
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# Course Outline (2001/12/28)

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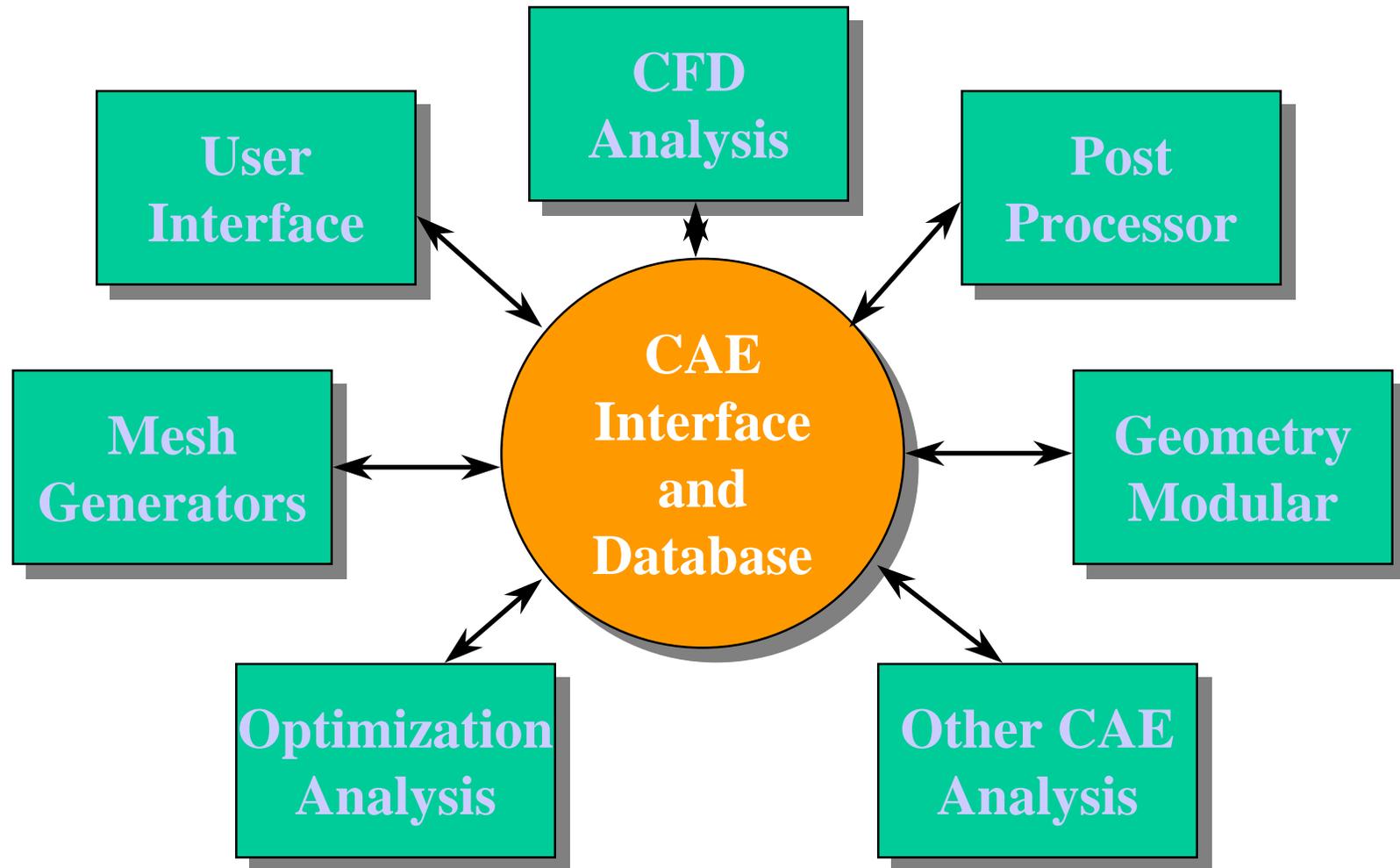
- The Requirement of CFD Software on Electronics
- **The Elements of CFD Software**
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# ELEMENTS OF CFD



# CFD IN CAE

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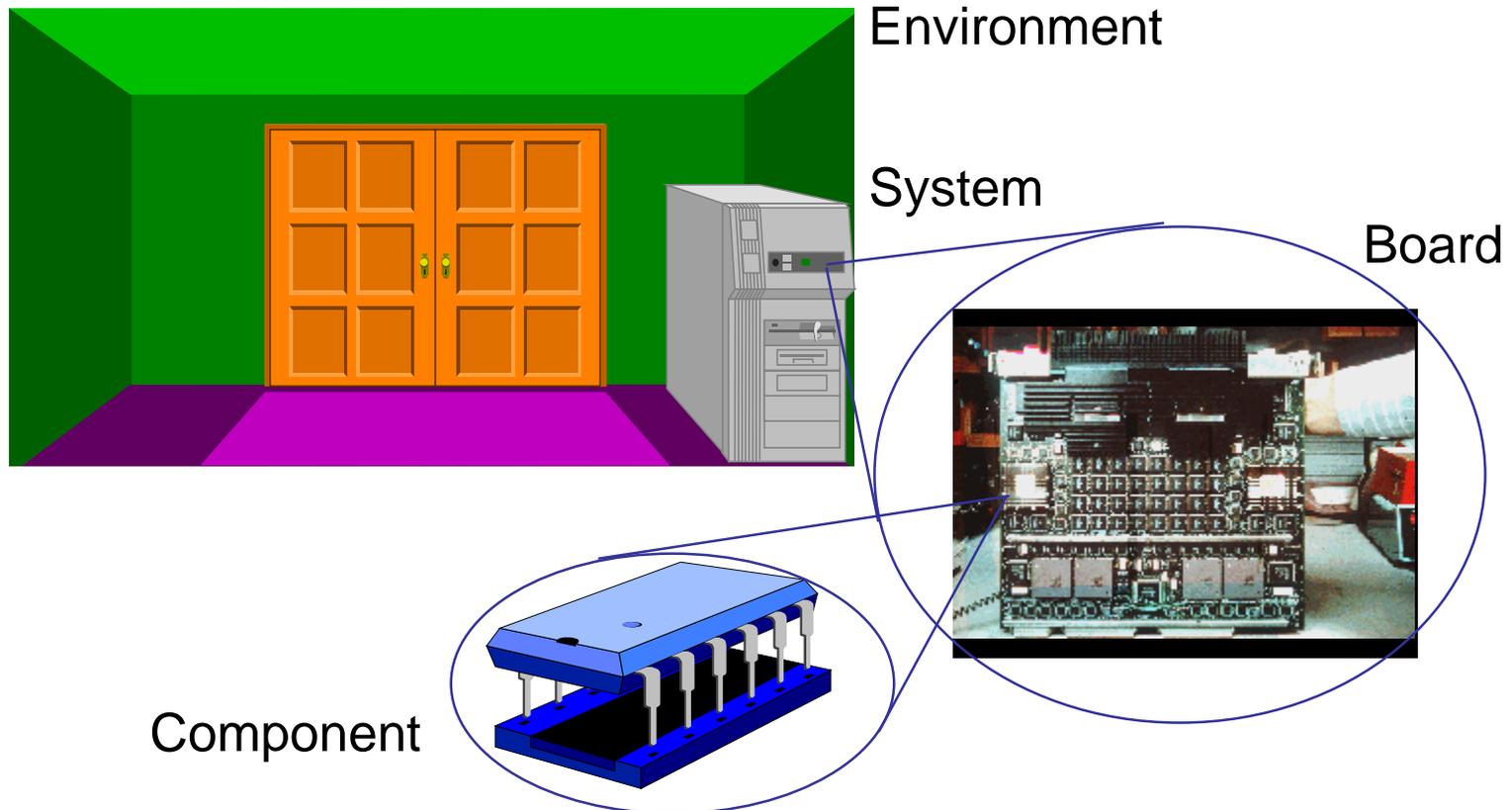
# Course Outline (2001/12/28)

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- The Requirement of CFD Software on Electronics
- The Elements of CFD Software
- **The Applications**
  - Component level
  - Board level
  - System level
  - Environment level
- Introduction to FLOTHERM®

# The Applications

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- Standards for exchange of thermal models throughout the supply chain
- Software and support for *design engineers*

# Some Examples

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## q Component Level

Analysis of Heat Fluxes from a PQFP (Flomerics)

## q Board Level

Design of a Processor Heatsink (Sequent Computers)

## q System Level

Radical Redesign of a PC Enclosure (Intel EUCD)

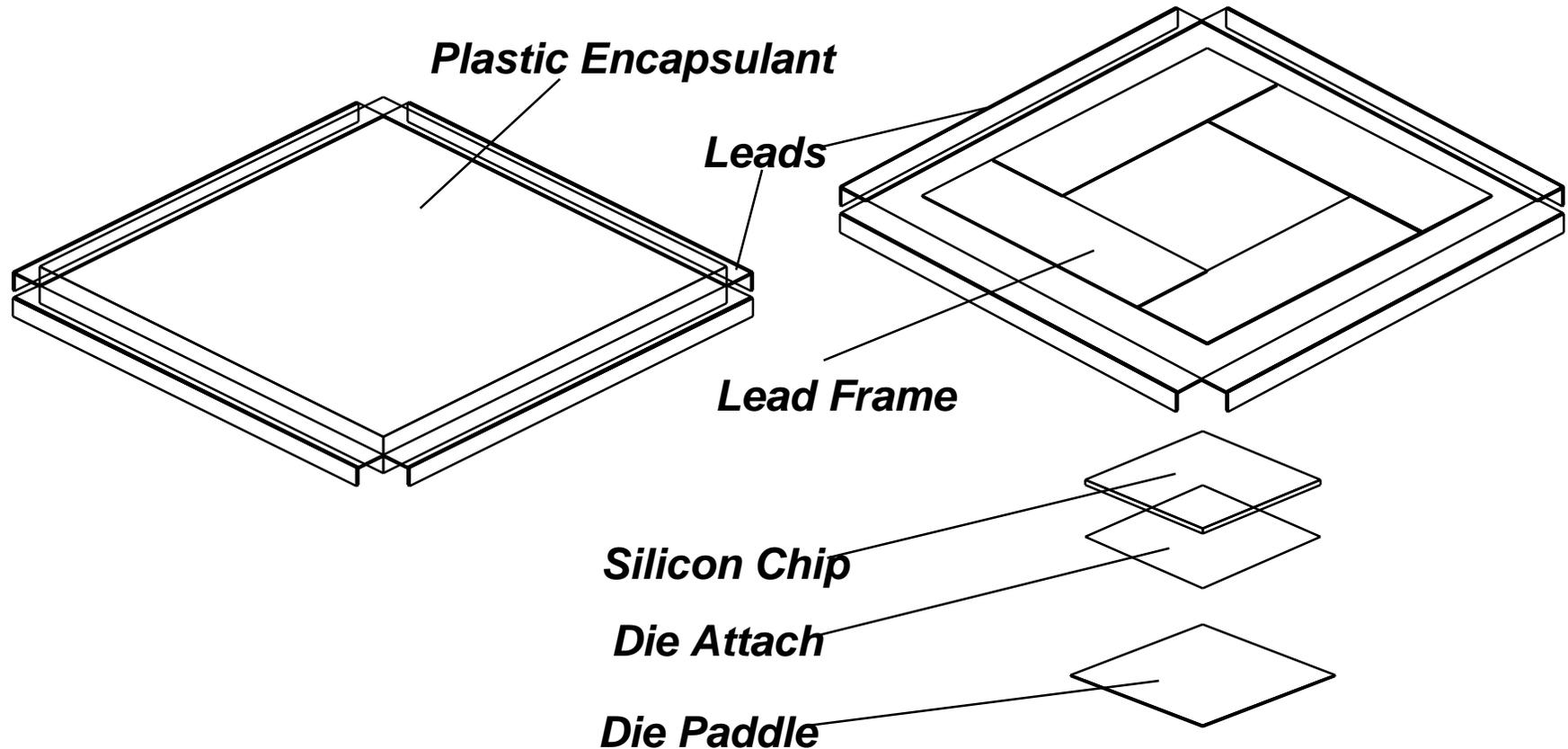
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# CFD Analysis of 208 Lead PQFP

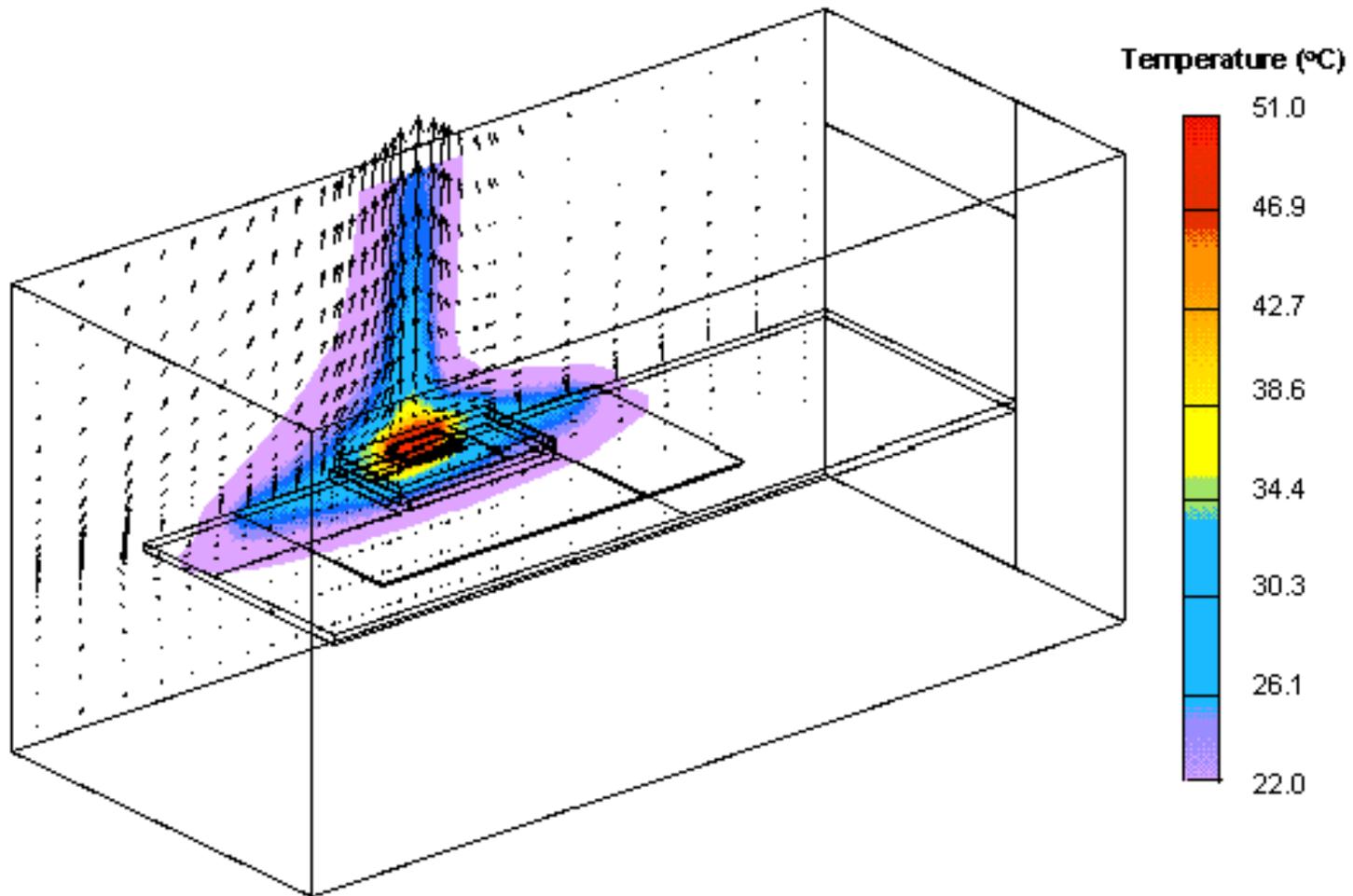
JEDEC JC15.1 Test Piece  
Energy Budget

# Model of 208-Lead PQFP - JEDEC Test Case

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# General View



# Results for 208-Lead PQFP

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Test conditions:

- Package mounted on JEDEC Low Conductivity test board
- mounted horizontally, in natural convection in small test chamber - ambient 20 °C

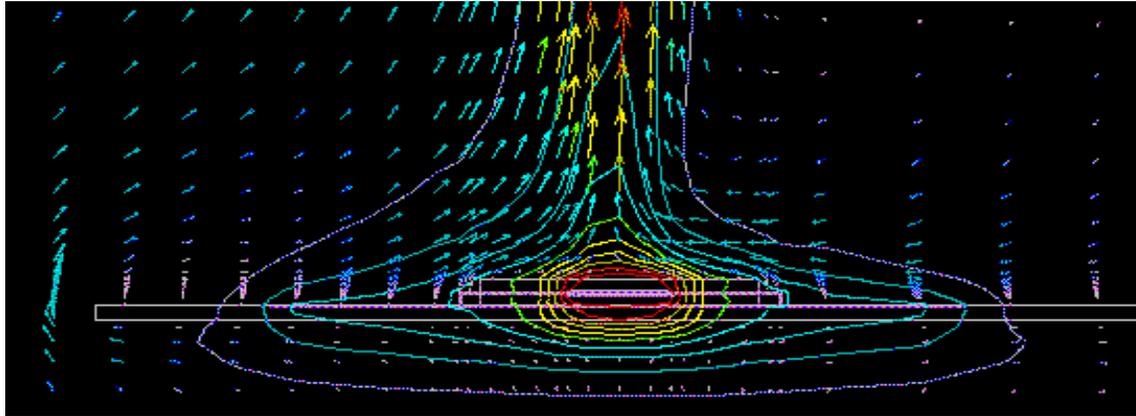
CFD predictions are compared with measured results from 8 JEDEC member companies

Junction Temperature		$R_{ja}$	
Measured	Simulation	Measured	Simulation
53 - 56°C	55°C	33 - 36°C/W	35°C/W

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# Breakdown of Energy Fluxes?

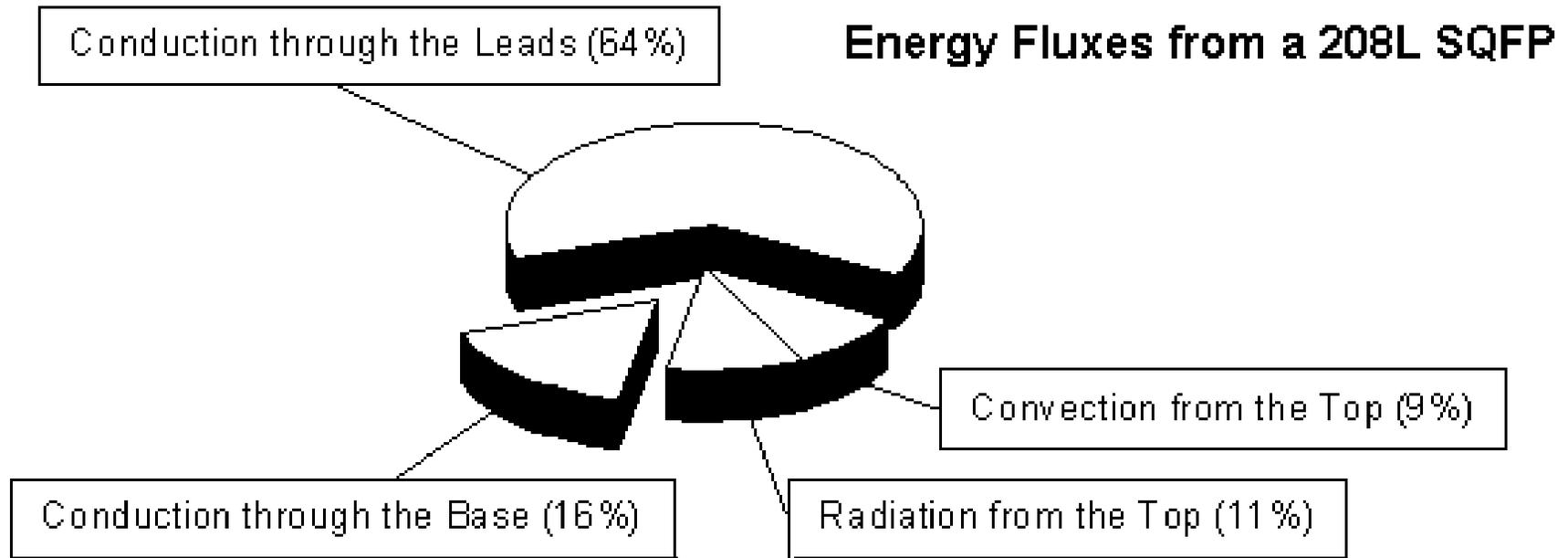
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- q Convection from the top
- q Radiation from the top
- q Conduction through the base
- q Conduction through leads

# Energy Flux Budget

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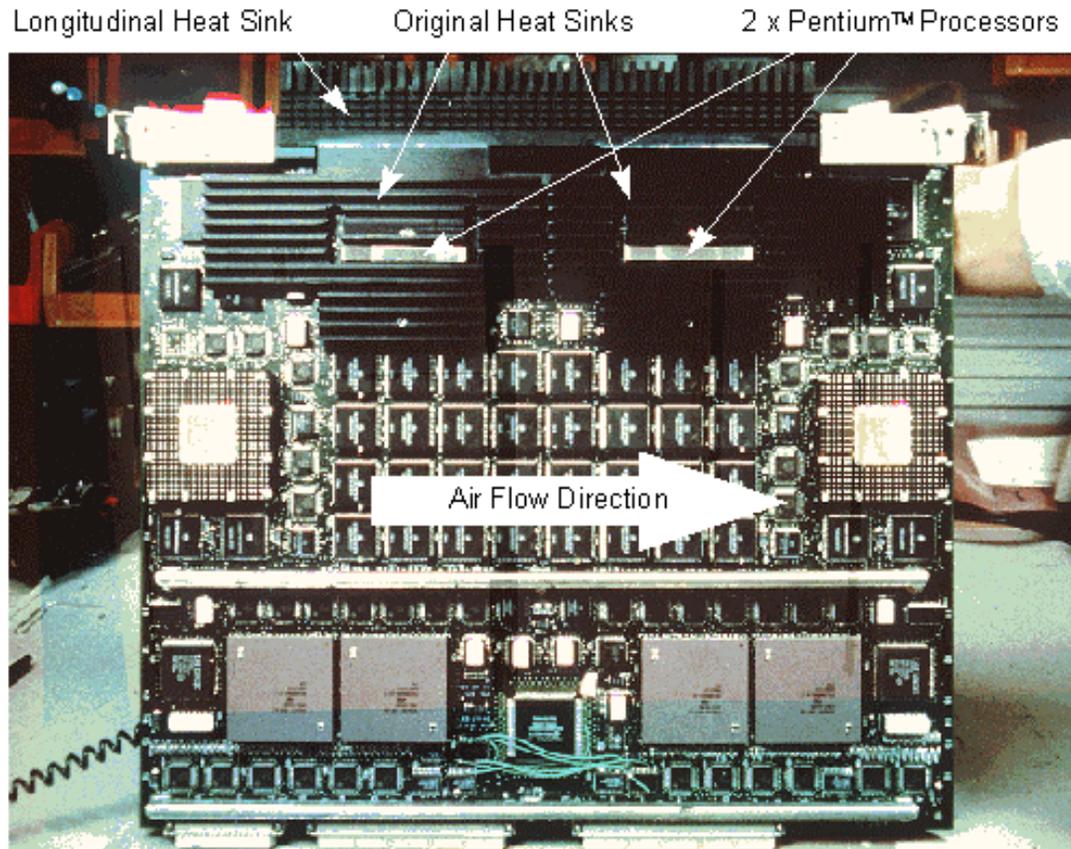


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# CFD Analysis of a Pentium™ Processor Card

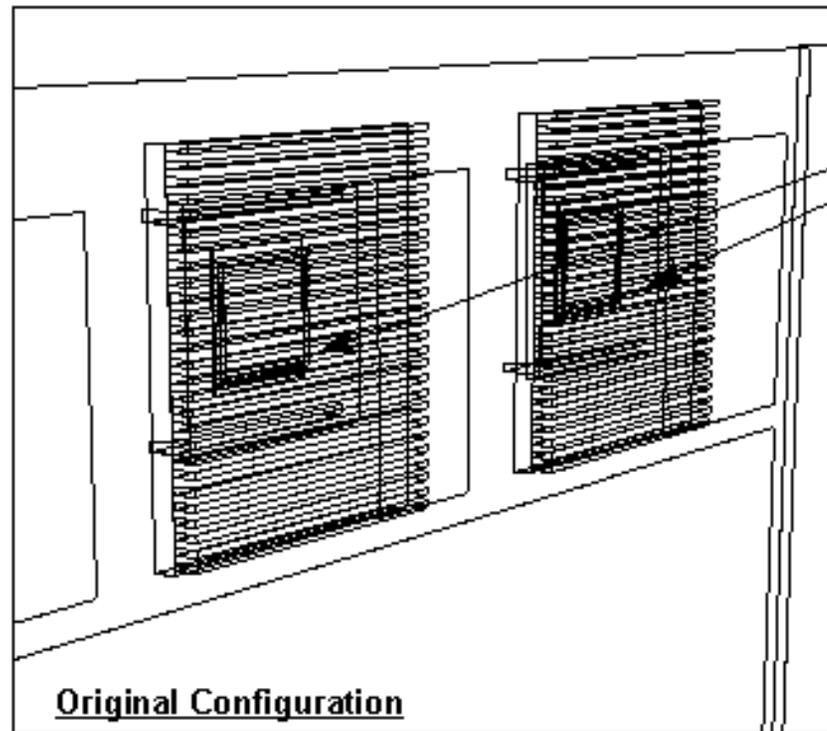
Dual Pentium Processors  
Re-Design of the Heatsink

# Basic Layout of the Card

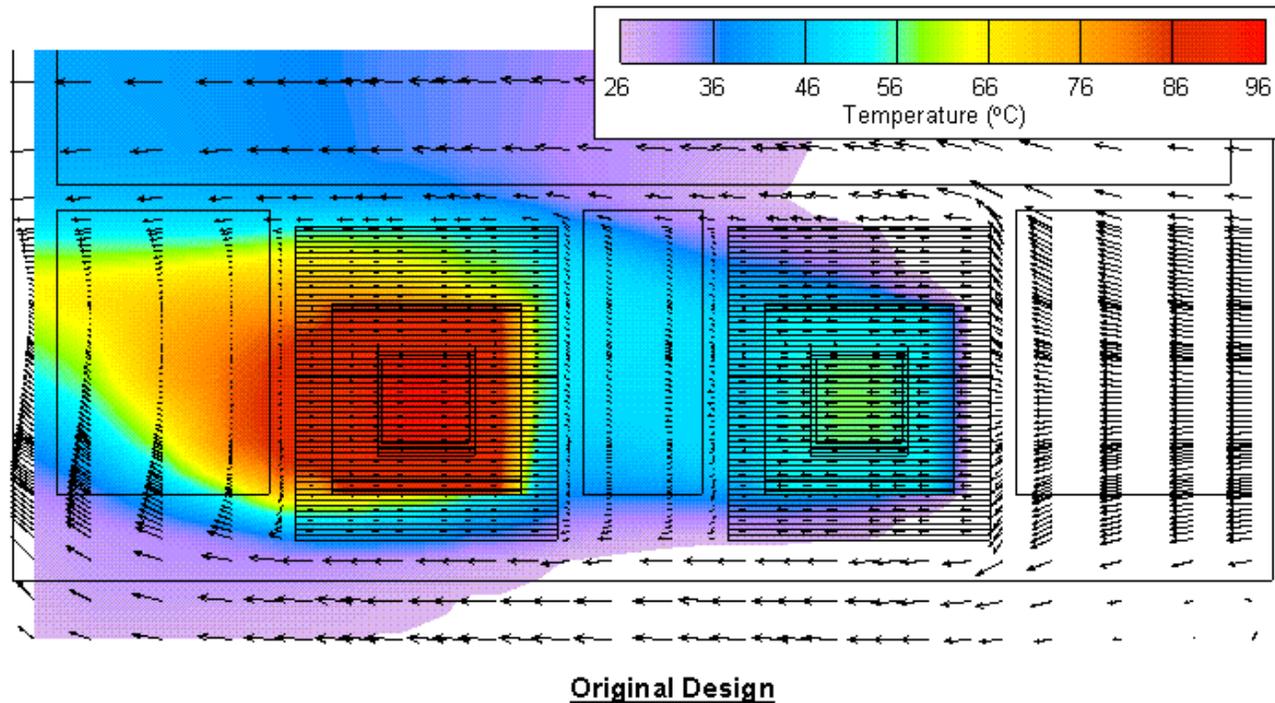


# Original Design of Processor Heatsinks

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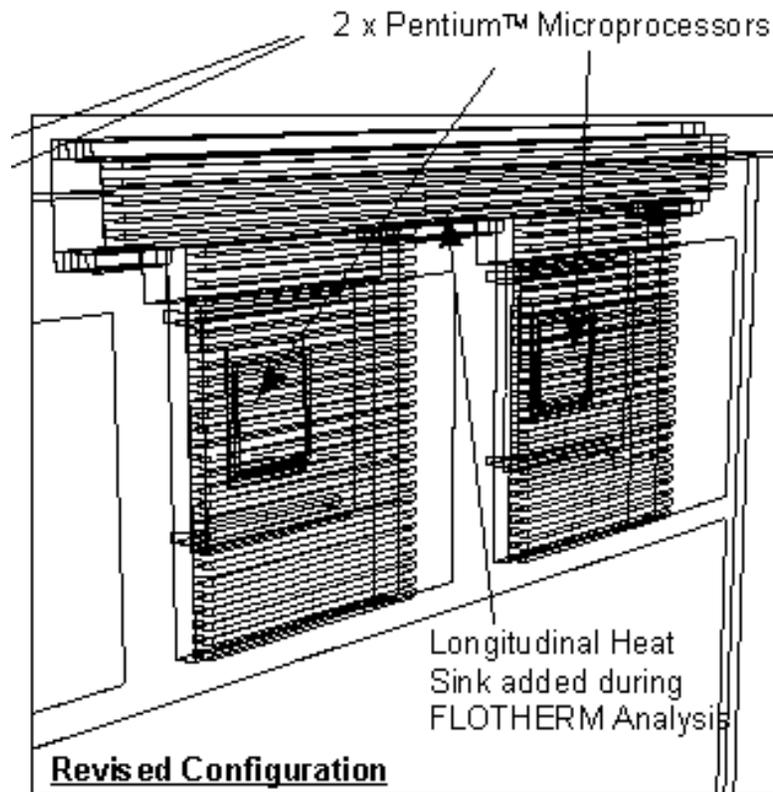


# Simulation Results

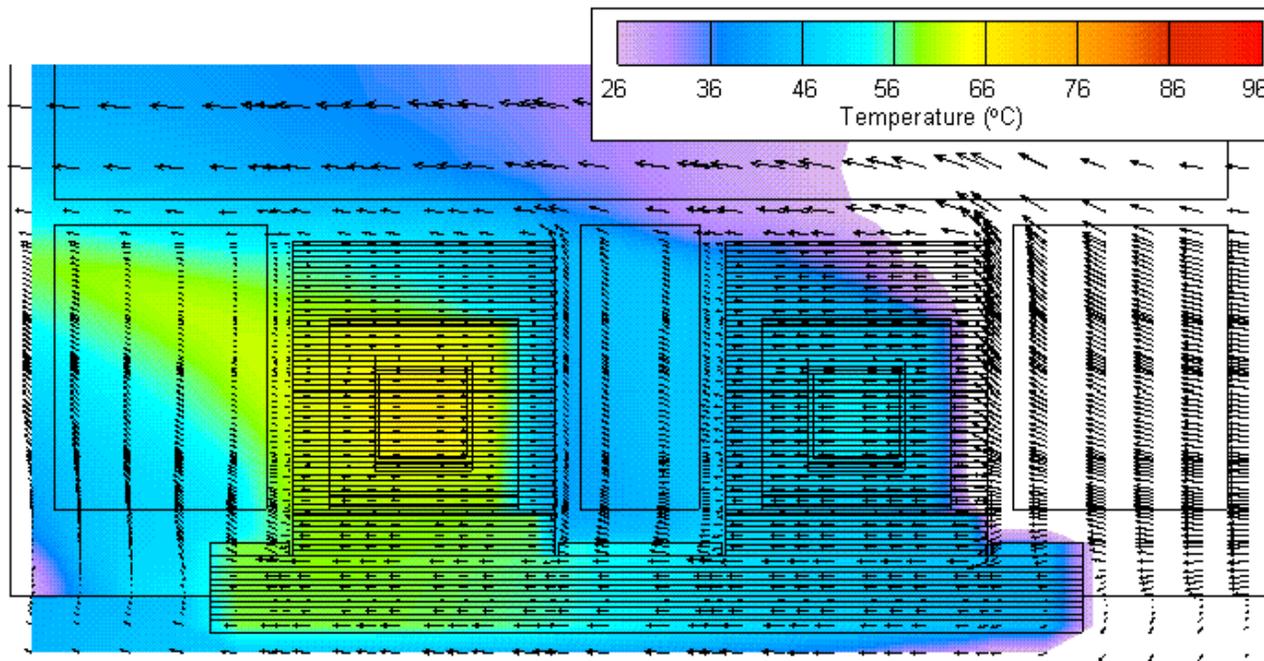


# Revised Design of Processor Heatsinks

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# Simulation Results



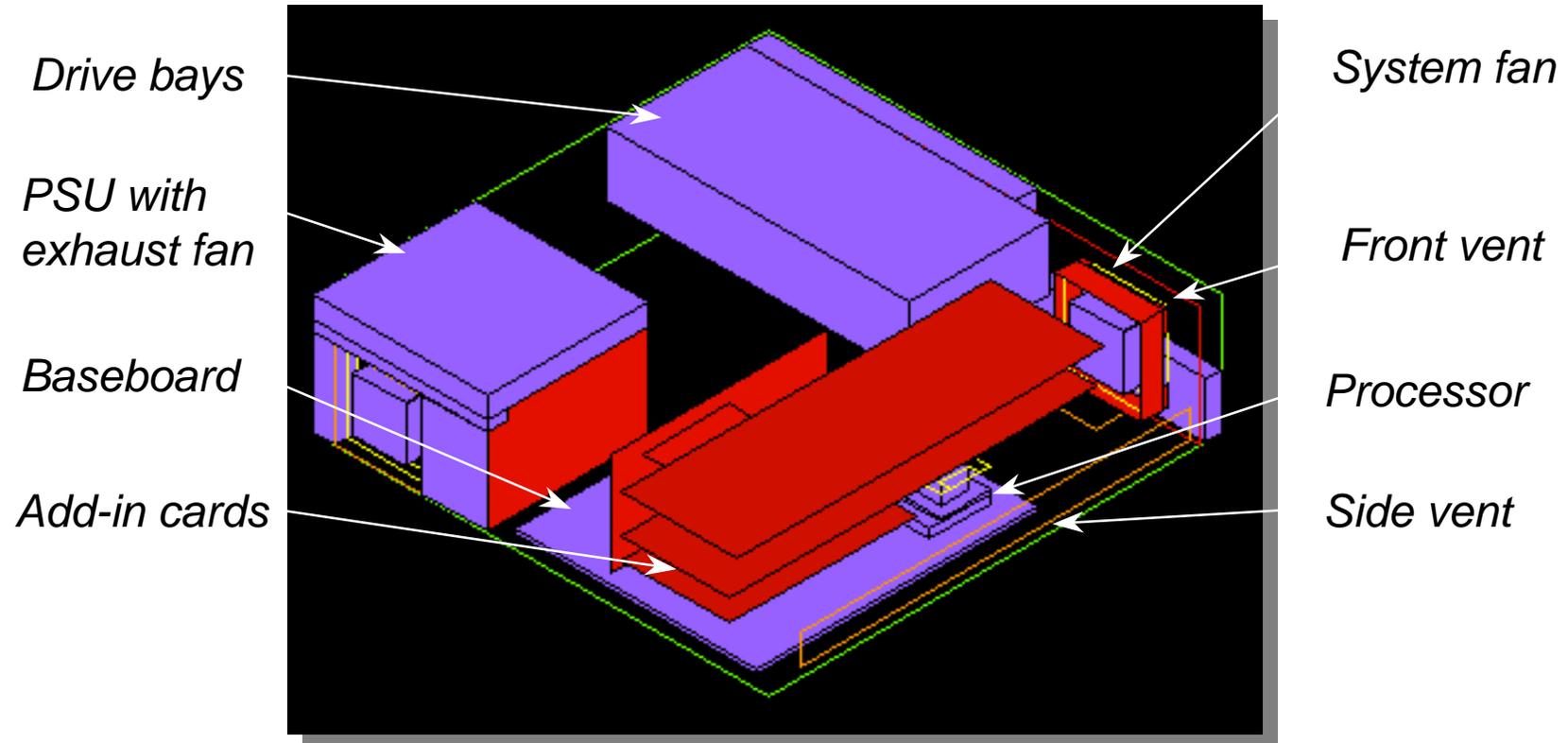
Revised Design

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# Radical Redesign of a Desktop PC Enclosure

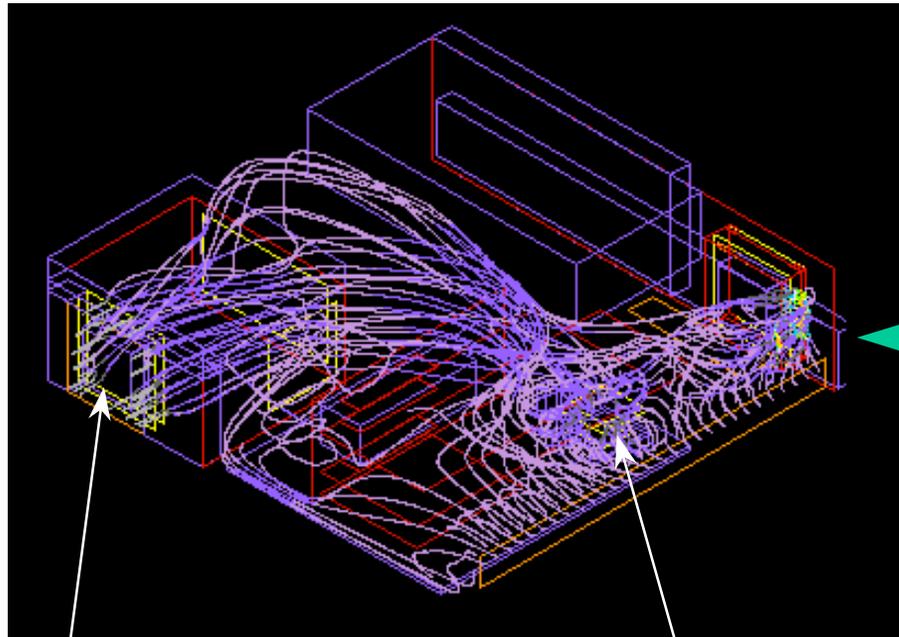
Eliminated the system fan but **still** improved  
overall thermal performance

# Desktop PC Enclosure



*Model includes all relevant sources of heat, vents, fans and obstructions.*

# System fan did not blow across processor site...

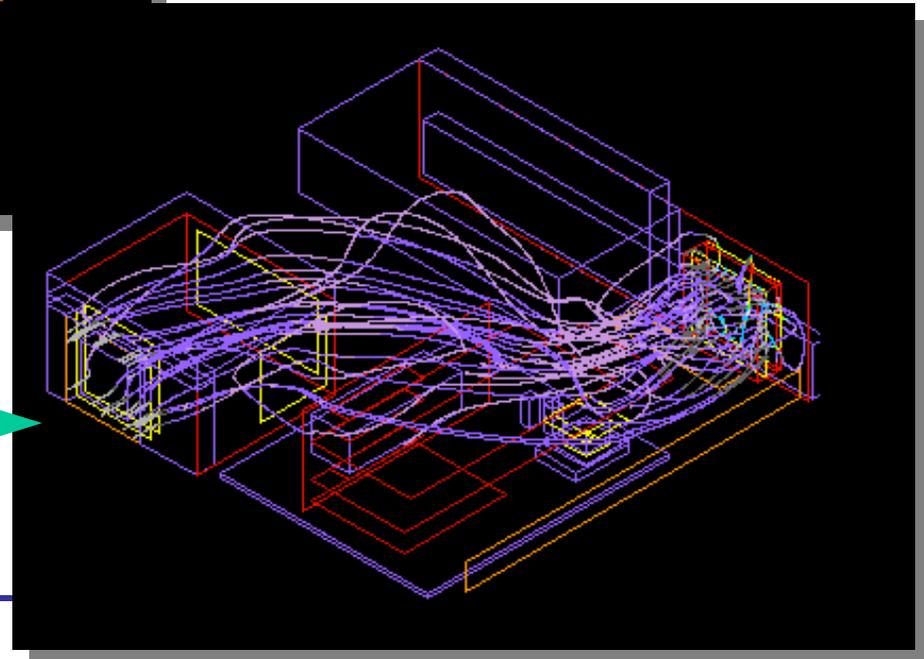


**PSU  
Fan**

**CPU**

**Most processor cooling air  
came from side vent**

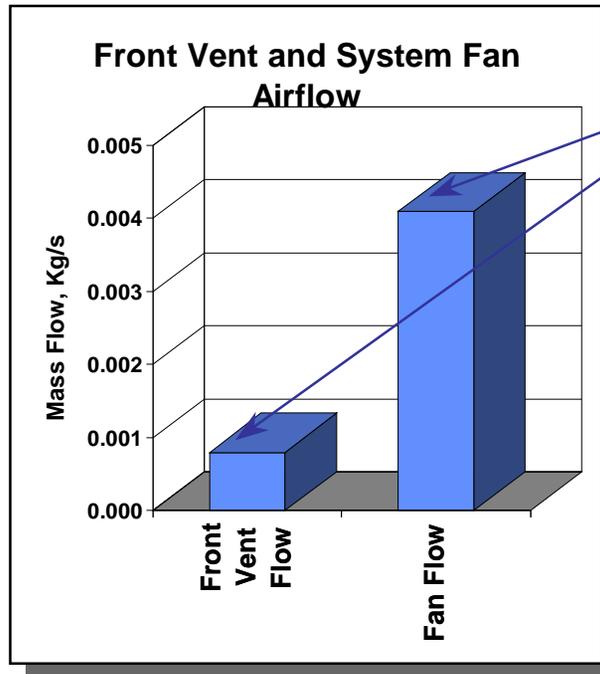
**Air from second fan went  
straight out the PSU!**



*Measurement and Simulation of  
Optomechatronic Systems*

Opto-Electronics Teaching Resources Center

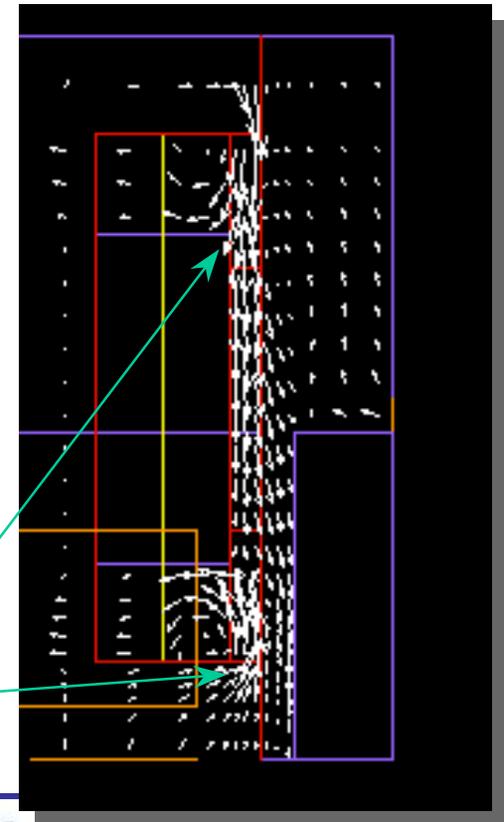
... and recirculated inside air



***These should be equal!***

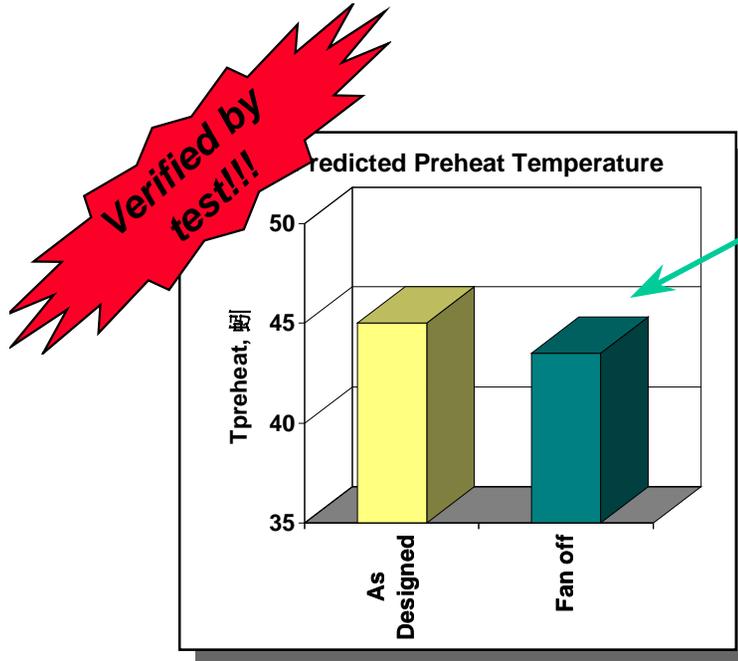
**What was the problem?**

- Inadequate front vents
- Fan mount design promoted recirculation



In fact, the fan made the processor  
run **WARMER!**

Processor temperature DROPPED  
about 1.5°C when  
fan was  
SHUT OFF!

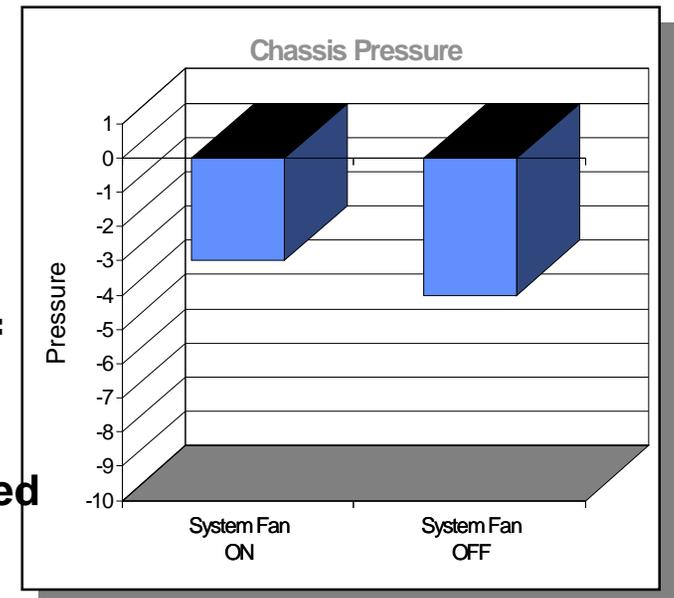


WHY?!?

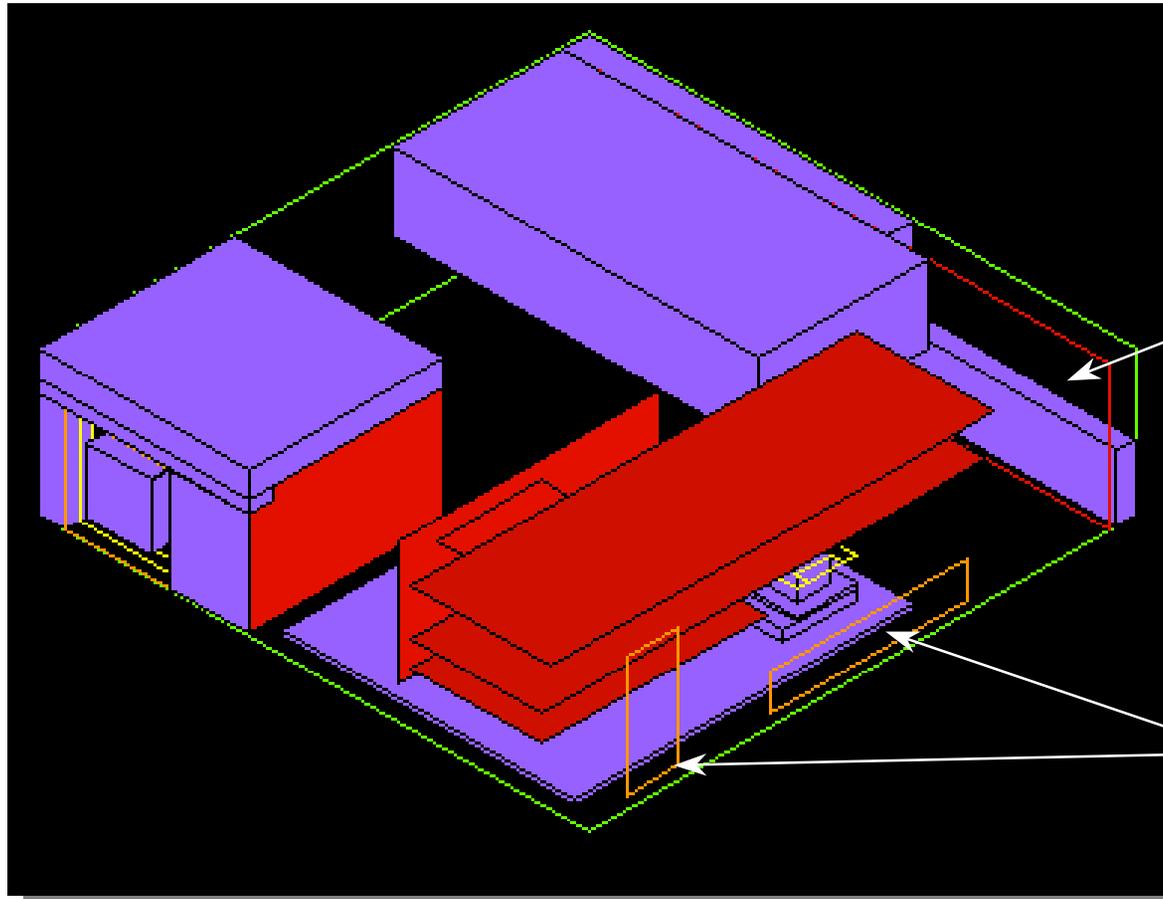
Side vent cools  
the processor

System fan off =  
lower chassis  
pressure

- More air sucked  
through side  
vent



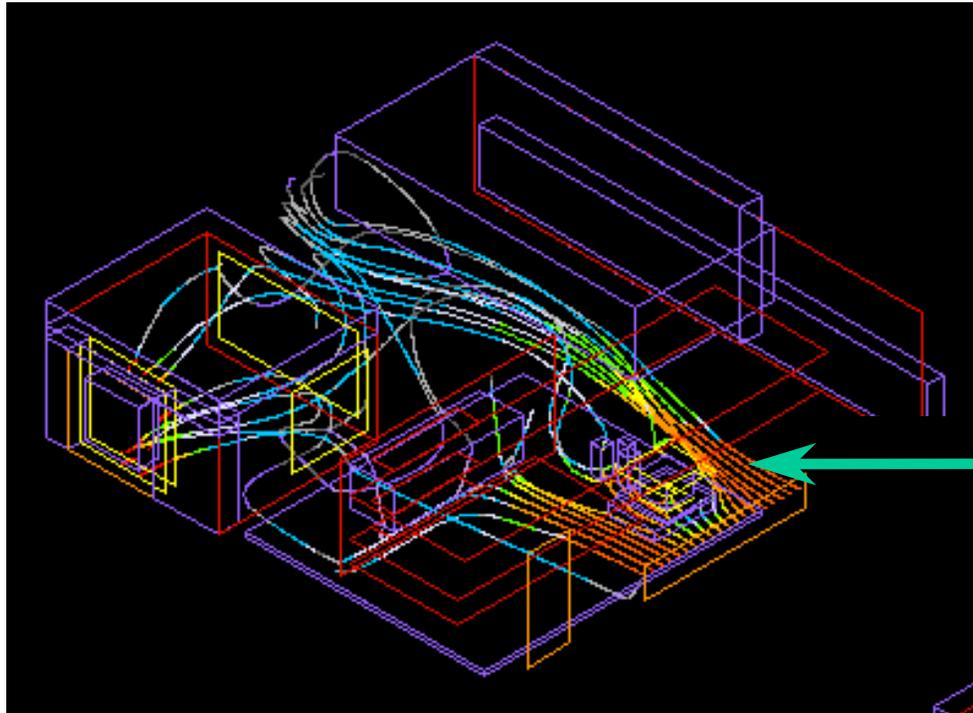
So, here's what was done to  
to fix this chassis...



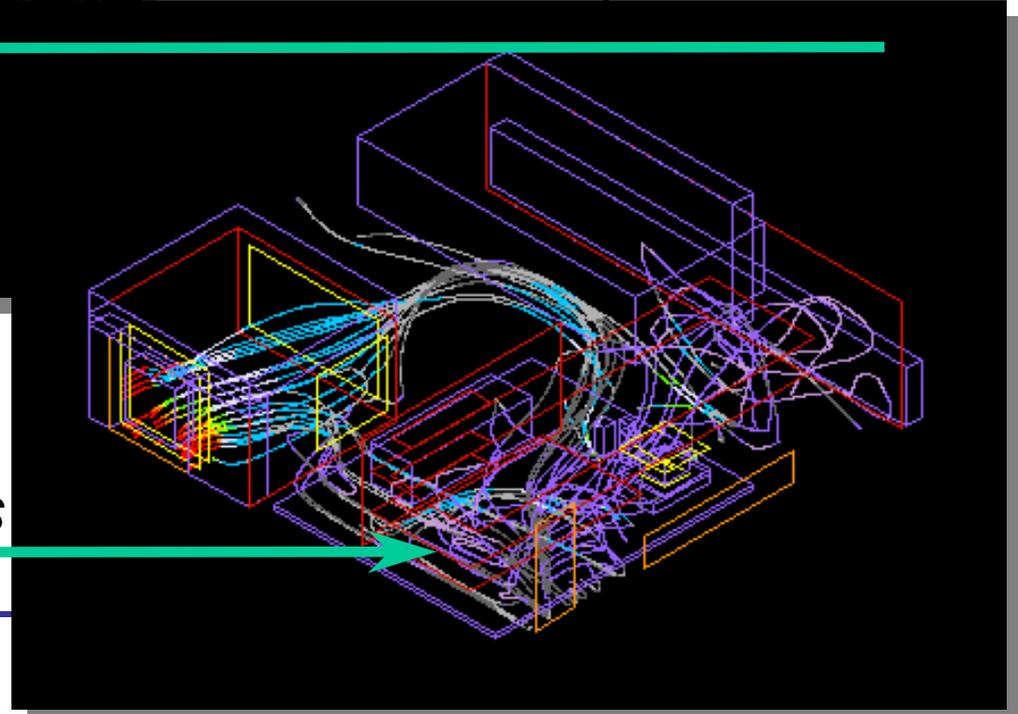
*System fan  
ELIMINATED  
and openings  
removed*

*Side vents  
optimized for  
processor location  
and add-in card  
cooling*

... and we got better flow and cooler temperatures



*Better flow over processor...*



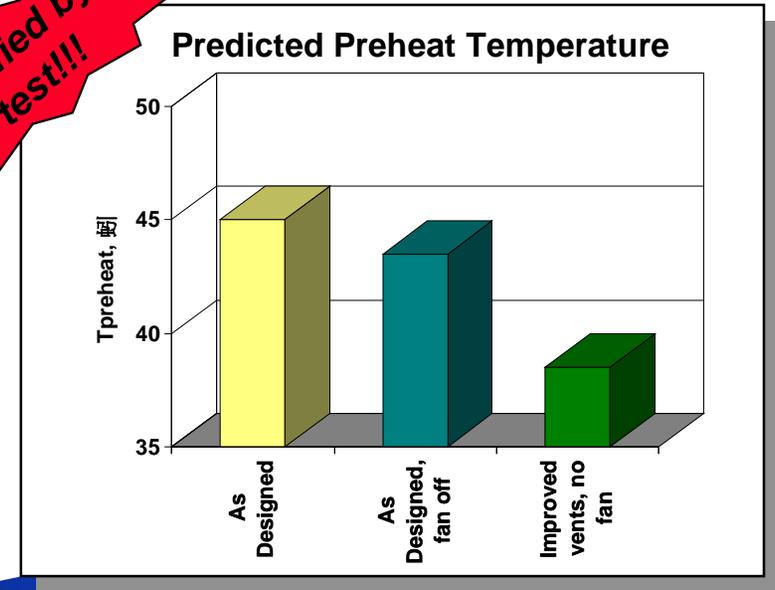
*...and add-in cards*

*Measurement and Simulation of  
Optomechatronic Systems*

# Eliminating fan and reducing vents improved this system's performance!

- System fan was counter-productive!
- Cooling performance improved by **REDUCING** venting

Verified by test!!!



**Saved cost of second fan**  
**Improved cooling**  
**Reduced acoustic noise**

# Conclusion

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- Hundreds of documented success stories
- Shown to reduce the cost and effort in the thermal design process

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